

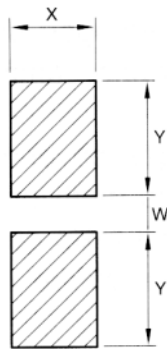
SOLDERING CONDITIONS



Recommended pad pattern and size (Vertical chip type)

● Standard type

Unit : mm



Case Size $\phi D \times L$	Land Size			Thin of Solder paste
	X	Y	W	
3×5.3	1.6	2.2	0.8	0.15
4×5.3, 5.7	1.6	2.6	1.0	0.15
5×5.3, 5.7	1.6	3.0	1.4	0.15
6.3×5.3, 5.7	1.6	3.6	1.9	0.15
6.3×7.7	1.6	3.6	1.9	0.15
8×6.5	1.6	4.0	2.1	0.15
8×10, 10.5	2.5	3.5	3.0	0.15
10×10, 10.5	2.5	4.0	4.0	0.15

Recommended soldering conditions

● Standard type

(1) Methods

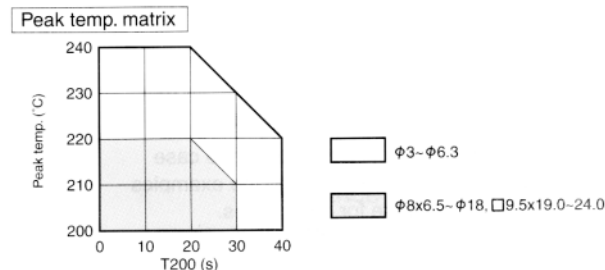
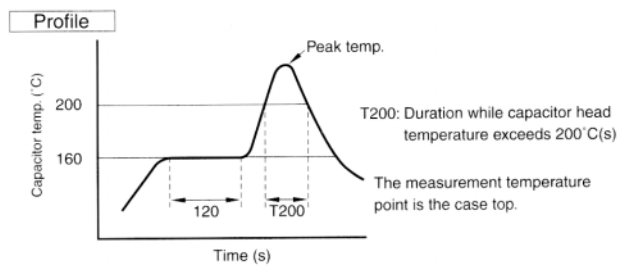
see the following

Methods	Reflow soldering	Soldering iron	Flow soldering
Advisability			×

(2) Soldering iron conditions

Iron tip temperature shall be 350 ± 5 within the duration of 3 seconds.

(3) Reflow soldering conditions



1. Preheating shall be under 160 within 120 seconds.
2. Peak temperature shall be within the peak temperature matrix.
3. For conditions exceeding the tolerances, consult with us.

● Lead-free type

(1) Methods

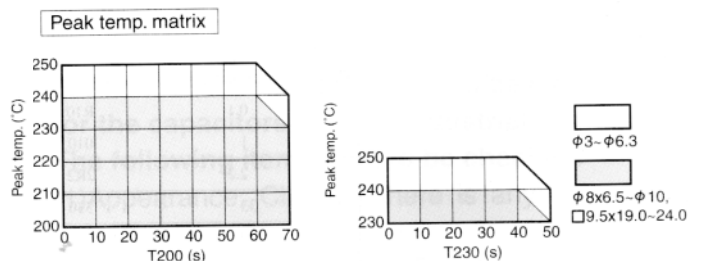
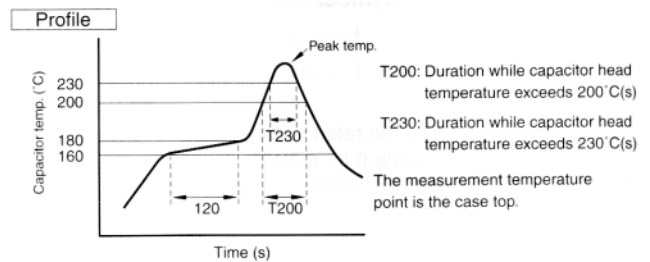
see the following

Methods	Reflow soldering	Soldering iron	Flow soldering
Advisability			×

(2) Soldering iron conditions

Iron tip temperature shall be 400 ± 5 within the duration of 3 seconds.

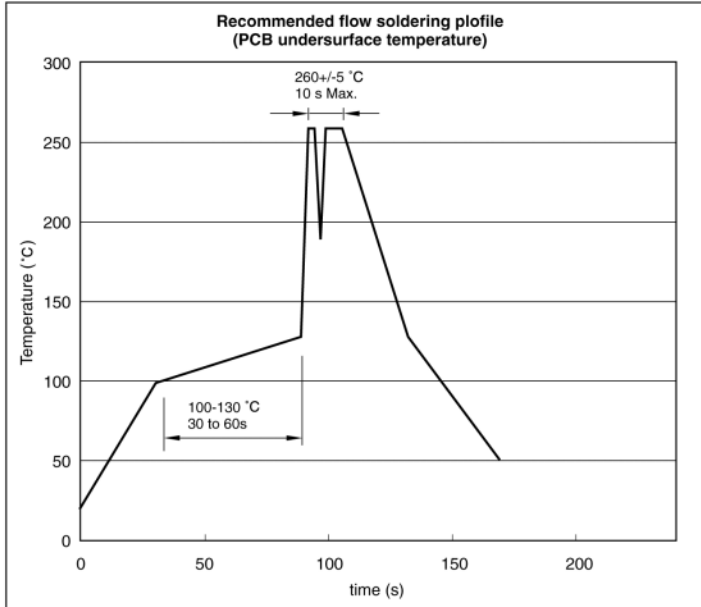
(3) Reflow soldering conditions



1. Preheating shall be under 180 within 120 seconds.
2. Peak temperature shall be within the peak temperature matrix.
3. For conditions exceeding the tolerances, consult with us.

Recommended soldering conditions (Pb-free flow soldering)

The recommendation soldering conditions of the product in which flow soldering is possible are as graph.



Caution for Using aluminum Electrolytic Capacitors

- (1) Do not dip the capacitor into melted solder.
- (2) Do not flux other part than the terminals.
- (3) If there is a direct contact between the sleeve of the capacitor and the printed circuit pattern or a metal part of another component such as a lead wire, it may cause shrinkage or crack.
- (4) If the application is for extended use, understand and manage the soldering characteristics to avoid abnormal current caused by a contact failure between the capacitor and the PCB.
- (5) Please refer to product specifications about other notes.